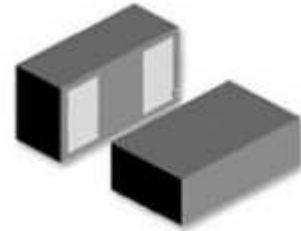


Description

This device is an ultra low capacitance PESD product designed to protect very high speed data interfaces. ECSD0402V24 has a typical capacitance of only 0.05pf (I/O to GND), and it can be used to meet the ESD immunity requirements of IEC61000-4-2 (15KV air, 8KV contact discharge).

ECSD0402V24



Schematic Diagram

Features

- ESD protection for high speed data lines to IEC61000-4-2
- ESD contact discharge typical 8KV, max 15KV
- ESD air discharge typical 15KV, max 25KV
- Surface mount
- Extremely low capacitance
- Very low leakage current
- Fast response time
- Bi-directional ESD protection
- Lead free solder termination
- The best ESD protection for high frequency, low voltage applications

Application

- High Definition Multi-Media Interface (HDMI)
- Digital Visual Interface (DVI)
- Display Port Interface (DP)
- Unified Display Interface (UDI)
- Mobile Display Digital Interface (MDDI)
- Gigabit Ethernet
- USB2.0 and USB3.0
- IEEE1394 interface

Absolute Maximum Ratings

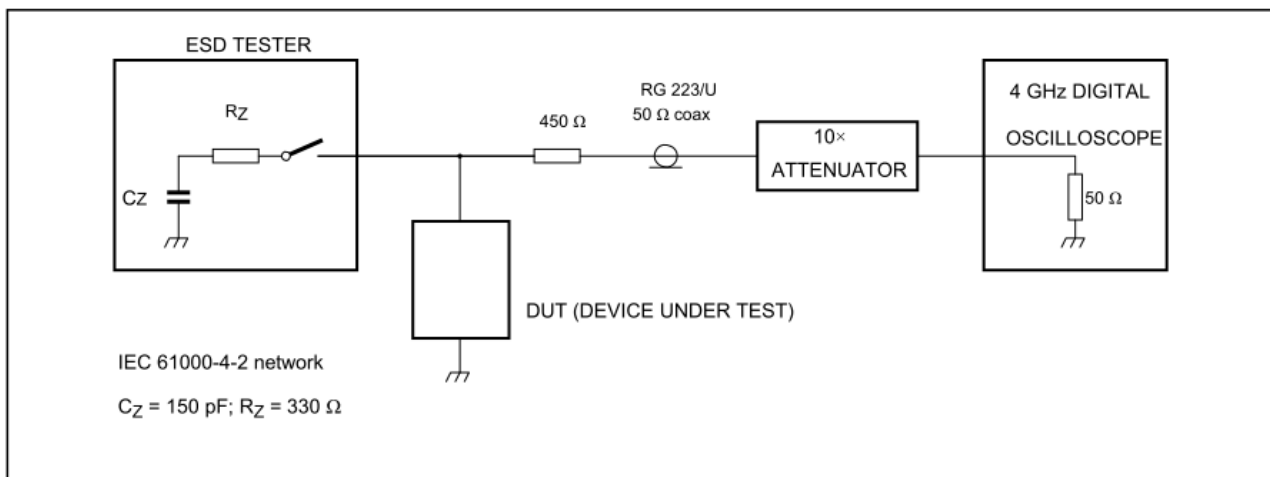
Parameter	Symbol	Value	Unit
Maximum Contact discharge voltage Per IEC61000-4-2	---	15KV	V
Maximum Air discharge voltage Per IEC61000-4-2	---	25KV	V
Maximum Operating temperature	TOPER	-40 to +90	°C
Maximum Storage temperature	TSTG	-55 to +125	°C
Maximum lead temperature for soldering during 10s	TL	260	°C

Electrical Characteristics (TA=25°C)

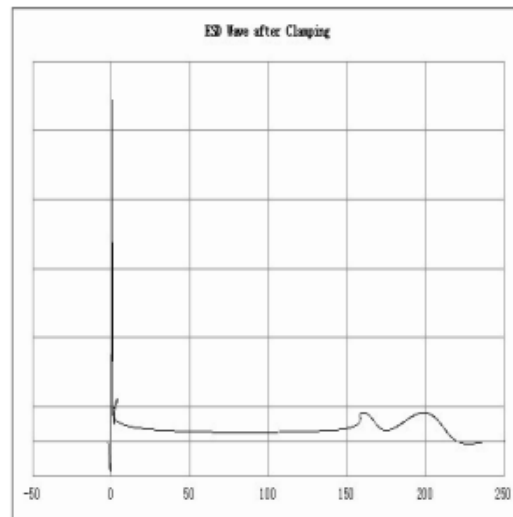
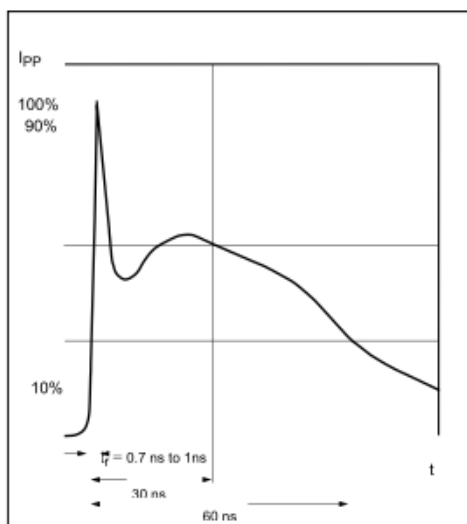
Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Rated Voltage	VR	---	---	---	24	V
Trigger voltage	VT	IEC61000-4-2 8KV contact discharge	---	350	---	V
Clamping voltage	VC	IEC61000-4-2 8KV contact discharge	---	35	---	V
Leakage current	IL	DC 5V shall be applied on component	---	---	0.10	uA
Capacitance	CP	VR = 0V, f = 1MHz	---	0.05	---	pF

- Note: 1. Trigger and clamping voltage are measured per IEC 61000-4-2, 8KV contact discharge method.
 2. After reliability tests such as high temp storage, temp cycles, continuous ESD strike etc, the maximum leakage current is less than 10uA.

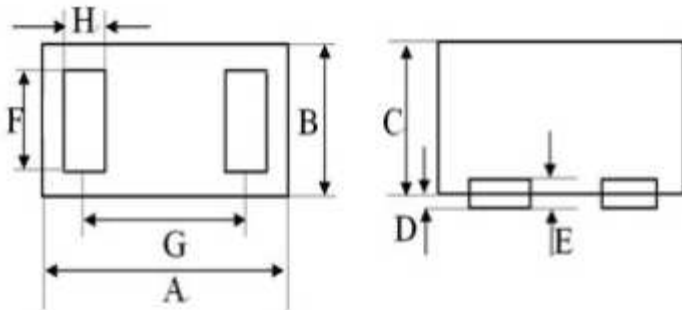
ESD Clamping Test



ESD Clamping Test Waveforms

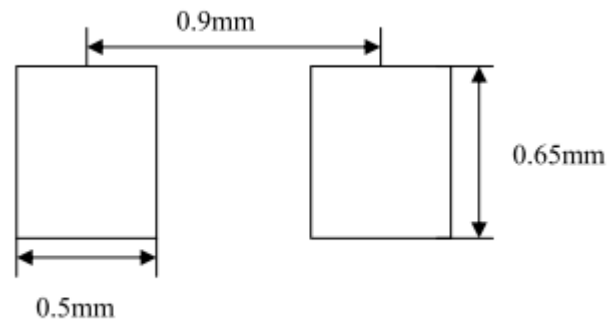


Product Dimension



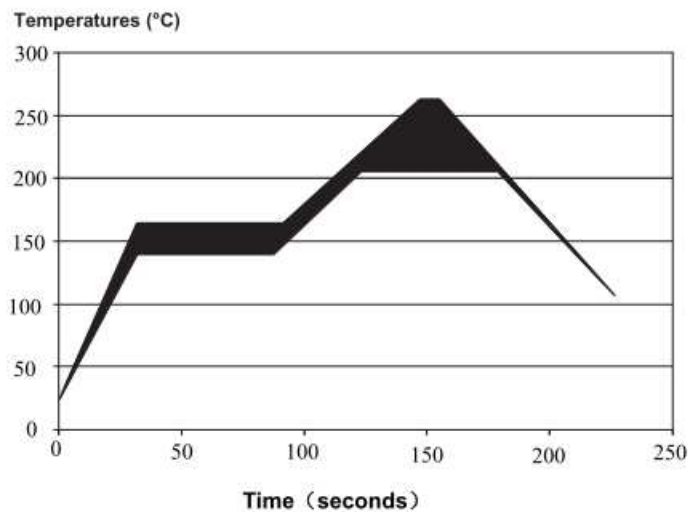
Dim	Millimeters	
	min	max
A	0.90	1.20
B	0.45	0.65
C	0.30	0.40
D	0.00	0.05
E	0.125REF	
F	0.40	0.50
G	0.65BSC	
H	0.25	0.35

PAD Dimension



Solder thickness 0.15 to 0.2mm

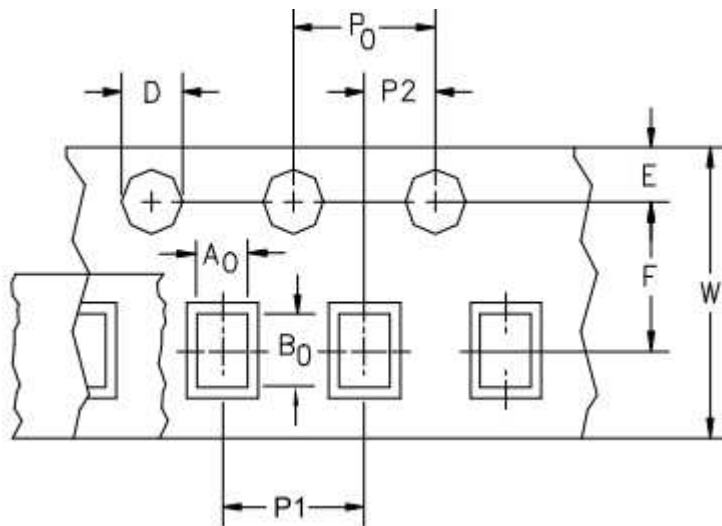
Solder Reflow Recommendations



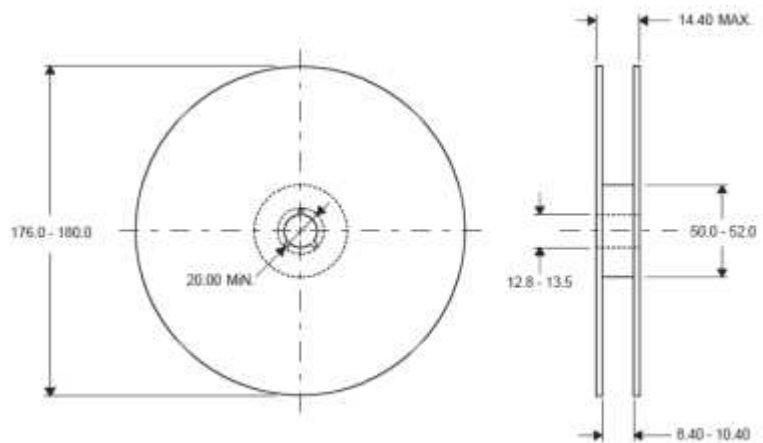
Order Information

Device	Package	Net Weight	Carrier	Quantity	HSF Status
ECSD0402V24	0402	0.44 mg	Tape & Reel	10,000pcs/reel	RoHS compliant

Package Information



Dimension	Typical	Unit
A0	0.75	mm
B0	1.22	
D	1.55	
P0	4.00	
P1	2.00	
P2	2.00	
E	1.75	
F	3.50	
W	8.00	



DIMENSIONS ARE: MILLIMETERS